


PRODUCT / PROCESS CHANGE INFORMATION

1. PCI basic data

1.1 Company		STMicroelectronics International N.V
1.2 PCI No.	ANALOG MEMS SENSORS/26/16311	
1.3 Title of PCI	Packing material change on TS922EIJT	
1.4 Product Category	See product list	
1.5 Issue date	2026-05-27	

2. PCI Team

2.1 Contact supplier	
2.1.1 Name	PIKE EMMA
2.1.2 Phone	+44 1628896111
2.1.3 Email	emma.pike@st.com
2.2 Change responsibility	
2.2.1 Product Manager	Marcello SAN BIAGIO
2.1.2 Marketing Manager	Lionel GRILLO
2.1.3 Quality Manager	Jean-Marc BUGNARD

3. Change

3.1 Category	3.2 Type of change	3.3 Manufacturing Location
Materials	Any indirect material modifications for shipping products in dimensions, material, composition, orientation	ST SHENZHEN -CHINA

4. Description of change

	Old	New
4.1 Description	T&R packing material : Std PE bag + no desiccants + 3M2671A cover tape	T&R packing material : Shielding bag + 2 desiccants + SP8025D cover tape
4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?	No impact	

5. Reason / motivation for change

5.1 Motivation	Implementation of an improved packing material to ensure optimal handling
5.2 Customer Benefit	QUALITY IMPROVEMENT

6. Marking of parts / traceability of change

6.1 Description	Internal traceability
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7. Timing / schedule

7.1 Date of qualification results	2026-04-21
7.2 Intended start of delivery	2026-05-05
7.3 Qualification sample available?	Upon Request

8. Qualification / Validation

8.1 Description	16311 PCN TS922EIJT Cover and dessicant.pptx - Read-Only.pdf		
8.2 Qualification report and qualification results	Available (see attachment)	Issue Date	2026-05-27

9. Attachments (additional documentations)

16311 Public product.pdf
16311 PCN TS922EIJT Cover and dessicant.pptx - Read-Only.pdf

10. Affected parts		
10.1 Current		10.2 New (if applicable)
10.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No
	TS922EIJT	

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